

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.81	100.0	2.9
			<b>Subtotal</b>	<b>0.81</b>	<b>100</b>	<b>2.9</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.04	100.0	0.15
	Pure metal	Aluminium (Al)	7429-90-5	0.14	100.0	0.5
			<b>Subtotal</b>	<b>0.18</b>	<b>200</b>	<b>0.65</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01	2.0	0.04
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.05
	Lead alloy	Lead (Pb)	7439-92-1	0.52	95.5	1.86
			<b>Subtotal</b>	<b>0.54</b>	<b>100</b>	<b>1.95</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	4.44	100.0	16
			<b>Subtotal</b>	<b>4.44</b>	<b>100</b>	<b>16</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.05
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01	0.03	0.05
	Copper alloy	Iron (Fe)	7439-89-6	0.05	0.1	0.18
	Copper alloy	Copper (Cu)	7440-50-8	49.23	99.84	177.32
			<b>Subtotal</b>	<b>49.3</b>	<b>100</b>	<b>177.6</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.79	4.0	6.44
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.71	15.0	24.16
	Filler	Silica fused	60676-86-0	33.1	74.0	119.21
	Flame retardant	Metal hydroxide		3.13	7.0	11.28
			<b>Subtotal</b>	<b>44.73</b>	<b>100</b>	<b>161.09</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>360.19</b>

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